HOLLOW YARN MEMBRANE MODULE AND ITS PREPARATION

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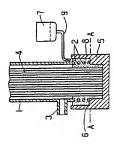
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Abstract of JP61222510

PURPOSE: To prevent the release of a resin layer from an outer cylinder by strongly adhering the resin layer to an outer cylinder, by integrating the resin layer fixing a hollow yam membrane bundle to the outer cylinder through piercing holes provided in the vicinity of both ends of the outer cylinder with the resin layer provided to the outside of the outer cylinder. CONSTITUTION:A hollow yarn membrane bundle 4 closed et both ends by heat sealing is inserted in an outer cylinder 1 having e lerge number of piercing holes 2 provided to both ends thereof so as to protrude the both ends of the vern membrane bundle 4 from both ends of the outer cylinder 1 end the lower end part of the outer cylinder 1 is covered with a cap 5 heving a step pert 6 provided to the inner periphery thereof and a liquid injection molding grede resin 8 is Injected in the cap 5 from e conteiner 7 through e tube 9. The resin is flow ed in the outer cylinder 1 from the plercing holes 2 to fill the space between the outer cylinder 1 and the hollow yarn membrane bundle 4, between yarn membranes end between the outside of the outer cylinder 1 and the inner surfece of the cap 5. After the resin 8 was cured, the cap 5 is detached end the end pert of the hollow yern membrane bundle 4 is cut along with the resin 8 to open the membrene end parts of seid membrane bundle 4. Next, the upper side of the bundle 4 is directed downwardly to receive the same operation. By this method, the release of the resin is not generated even in a cooling process after high temp, sterilization,



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